

IC CARD

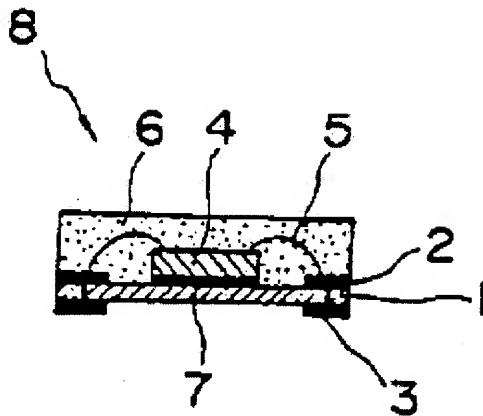


Patent number: JP3112688
Publication date: 1991-05-14
Inventor: KUWABARA TSUMORU
Applicant: ASAHI CHEM IND CO LTD
Classification:
 - **international:** B42D15/10
 - **european:**
Application number: JP19890249335 19890927
Priority number(s):

Abstract of JP3112688

PURPOSE: To thin the thickness of an IC module and to obtain a mass-IC memory card by mounting the IC module, which mounts an IC chip on a patterned printed board having not more than specific thickness dimension and which resin-seals only the IC-chip-mounting surface, in a card.

CONSTITUTION: In an IC module 8 built in an IC card, a thin printed board with a thickness of not more than 200 μm having a conductive layer, e.g. a copper foil is patterned on a substrate 1 composed of an insulating material and a bonding terminal 2 is provided on the mounting side of a chip 4. Also, a connection terminal 3 is provided via a through hole. The chip 4 is bonded onto the substrate 1 by an adhesive 7 and connected with the bonding terminal 2 for the chip 4 by a wire 5 and the side for mounting the IC chip 4 is resin-sealed, e.g. by epoxy resin 6 so that the wire and IC chip are covered and protected sufficiently. The thickness of the whole module 8 is thinned to 700 μm or below.



Data supplied from the esp@cenet database - Patent Abstracts of Japan